



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

CASE NO.	948J-01
STATUS	ON SEMICONDUCTOR STANDARD
NEW STD	
USED ON	8 LD TSSOP, PITCH 0.65MM

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MM.
 3. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15(.006) PER SIDE.
 4. DIMENSION "B" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25(.010) PER SIDE.
 5. DIMENSION "K" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08(.003) TOTAL IN EXCESS OF THE "K" DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION "A" AND "B" ARE TO BE DETERMINED AT DATUM PLANE **-W-**



DOCUMENT NUMBER	98ASH70382A
SHEET 2 OF 2	

ISSUE	REVISION	COORD/ DATE
A	REDRAWN AND SET UP ELECTRONICALLY. REQ BY K. MARTIN	FB 09 JAN 02